

Abstract

The invention relates to a thermode device for connecting and/or electrically contacting a plurality of first semiconductor components to at least one support element and/or to a plurality of second semiconductor components by heating an adhesive under the application of pressure, wherein the thermode device (1) comprises a basic body (2, 3, 4) and a heating element (7) which can be extended out of the basic body (2, 3, 4) and which, under the application of pressure, acts on at least one of the first semiconductor components, wherein the basic body (2, 3, 4) has on its underside a plurality of heating plates (5) which are oriented vertically and are arranged next to one another, wherein each heating plate (5) has on its end and underside (5a) a plurality of the extendable heating elements (7), to the underside of each of which there is assigned a first semiconductor component.

(Fig. 1)
